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(71) Applicant (for all designated States except US): **3M INNOVATIVE PROPERTIES COMPANY** [US/US];
3M Center, Post Office Box 33427, Saint Paul, Minnesota
55133-3427 (US).

(72) Inventors: **FREY, Matthew H.**; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).
NGUYEN, Khanh P.; 3M Center, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).

(74) Agents: **LOWN, Jean A.** et al.; 3M Center, Office of Intellectual Property Counsel, Post Office Box 33427, Saint Paul, Minnesota 55133-3427 (US).

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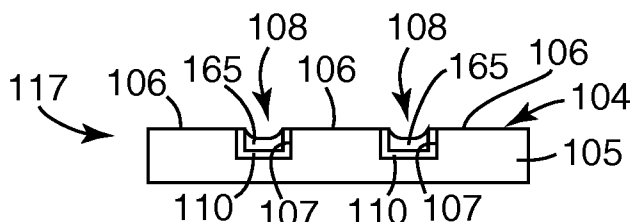
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functionalized raised region and an unfunctionalized recessed region, and depositing electrolessly a deposit metal selectively on the unfunctionalized recessed region.

(57) Abstract: A method of patterning a deposit metal on a polymeric substrate is described. The method includes providing a polymeric film substrate having a major surface with a relief pattern having a recessed region and an adjacent raised region, depositing a first material onto the major surface of the polymeric film substrate to form a coated polymeric film substrate, forming a layer of a functionalizing material selectively onto the raised region of the coated polymeric film substrate to form a

METHODS OF PATTERNING A DEPOSIT METAL ON A POLYMERIC SUBSTRATE

BACKGROUND

5 The present disclosure relates generally to methods of patterning a deposit metal on a polymeric substrate and articles formed by such methods.

 Polymeric films with patterns of metallic material have a wide variety of commercial applications. In some instances, it is desired that a conductive grid be sufficiently fine to be invisible to the unaided eye and supported on a transparent
10 polymeric substrate. Transparent conductive sheets have a variety of uses including, for example, resistively heated windows, electromagnetic interference (EMI) shielding layers, static dissipating components, antennas, touch screens for computer displays, and surface electrodes for electrochromic windows, photovoltaic devices, electroluminescent devices, and liquid crystal displays.

15 The use of essentially transparent electrically conductive grids for such applications as EMI shielding is known. The grid can be formed from a network or screen of metal wires that are sandwiched or laminated between transparent sheets or embedded in substrates (U.S. Pat. Nos. 3,952,152; 4,179,797; 4,321,296; 4,381,421; 4,412,255). One disadvantage of using wire screens is the difficulty in handling very fine wires or in
20 making and handling very fine wire screens. For example, a 20 micrometer diameter copper wire has a tensile strength of only 1 ounce (28 grams force) and is therefore easily damaged. Wire screens fabricated with wires of 20 micrometer diameter are available but are expensive due to the difficulty in handling very fine wire.

 Rather than embed a preexisting wire screen into a substrate, a conductive pattern
25 can be fabricated in-situ by first forming a pattern of grooves or channels in a substrate and then filling the grooves or channels with a conductive material. This method has been used for making conductive circuit lines and patterns by a variety of means, although usually for lines and patterns on a relatively coarse scale. The grooves can be formed in the substrate by molding, embossing, or by lithographic techniques. The grooves can then
30 be filled with conductive inks or epoxies (U.S. Pat. No. 5,462,624), with evaporated, sputtered, or plated metal (U.S. Pat. Nos. 3,891,514; 4,510,347; and 5,595,943), with molten metal (U.S. Pat. No. 4,748,130), or with metal powder (U.S. Pat. Nos. 2,963,748; 3,075,280; 3,800,020; 4,614,837; 5,061,438; and 5,094,811). Conductive grids on

polymer films have been made by printing conductive pastes (U.S. Pat. No. 5,399,879) or by photolithography and etching (U.S. Pat. No. 6,433,481). These prior art methods have limitations. For example, one problem with conductive inks or epoxies is that the electrical conductivity is dependent on the formation of contacts between adjacent
5 conductive particles, and the overall conductivity is usually much less than that of solid metal. Vapor deposition of metal or electroplating is generally slow and often requires a subsequent step to remove excess metal that is deposited between the grooves. Molten metal can be placed in the grooves but usually requires the deposition of some material in the grooves that the metal will wet. Otherwise the molten metal will not penetrate nor stay
10 in the grooves due to surface tension of the molten metal.

In addition to conductive grids, polymer films supporting patterns of conductive materials in the form of electrical circuits are also useful. Flexible circuitry is used in the support and interconnection of electronic components, as well as in the fabrication of sensors. Examples of sensors include environmental sensors, medical sensors, chemical
15 sensors, and biometric sensors. Some sensors are preferably transparent. As in the case of conductive grids, flexible circuits on polymer film substrates are often fabricated using photolithography, which includes multiple steps of photoresist placement, exposure, development, and removal. Alternative methods that do not require such expensive equipment and so many fabrication process steps are desired in the industry.

Circuits have been made by placing metal powder into grooves followed by
20 compacting the powder to enhance electrical contact between the particles. Lillie et al. (U.S. Pat. No. 5,061,438) and Kane et al. (U.S. Pat. No. 5,094,811) have used this method to form printed circuit boards. However, these methods are not practical for making fine circuits and fine metal patterns. On a fine scale, replacing or re-registering the tool over
25 the embossed pattern to perform the metal compaction can be difficult. For example, a sheet with a pattern of 20 micrometer wide channels would require that the tool be placed over the pattern to an accuracy of roughly 3 micrometers from one side of the sheet to the other. For many applications, the sheet may be on the order of 30 cm by 30 cm. Dimensional changes due to thermal contraction of a thermoplastic sheet are typically
30 about 1 percent or more during cooling from the forming temperature to room temperature. Thus, for a 30 cm by 30 cm sheet, a contraction of 1 percent would result in

an overall shrinkage of 0.3 cm. This value is 1000 times larger than the 3 micrometer placement accuracy needed, making accurate repositioning of the tool difficult.

SUMMARY

5 The present disclosure relates to methods of patterning a deposit metal on a polymeric substrate. In particular, the present disclosure relates to methods of patterning a deposit metal on a polymeric substrate by selectively transferring a functionalizing material onto raised regions of a polymer film substrate with an essentially featureless printing plate and then electrolessly depositing a metal onto un-functionalized regions
10 (recessed regions or not raised regions). This new approach allows fine-scale patterns of functionalizing material and deposit metals to be continuously transferred at high rates to web substrates with little regard for synchronization of a roll-to-roll apparatus.

 In one exemplary implementation, a method of patterning a deposit metal on a polymeric substrate is described. The method includes providing a polymeric film
15 substrate having a major surface with a relief pattern having a recessed region and an adjacent raised region, depositing a first material onto the major surface of the polymeric film substrate to form a coated polymeric film substrate, forming a layer of a functionalizing material selectively onto the raised region of the coated polymeric film substrate to form a functionalized raised region and an unfunctionalized recessed region,
20 and depositing electrolessly a deposit metal selectively on the unfunctionalized recessed region.

 The present disclosure also relates to an article comprising a polymeric film having a major surface with a relief structure including a raised region and an adjacent recessed region, and functionalizing molecules selectively placed onto the raised region.

25 These and other aspects of the methods and articles according to the subject invention will become readily apparent to those of ordinary skill in the art from the following detailed description together with the drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

30 The invention may be more completely understood in consideration of the following detailed description of various embodiments of the invention in connection with the accompanying drawings, in which:

FIGs. 1A-1H is a schematic diagram of an illustrative method of patterning a material on a polymeric substrate;

FIGs. 2A-2G is a schematic diagram of another illustrative method of patterning a material on a polymeric substrate; and

5 **FIG. 3** is a schematic diagram of an illustrative roll-to-roll apparatus.

While the invention is amenable to various modifications and alternate forms, specifics thereof have been shown by way of example in the drawings and will be described in detail. It should be understood, however, that the intention is not to limit the invention to the particular embodiments described. On the contrary, the intention is to
10 cover all modifications, equivalents, and alternatives falling within the spirit and scope of the invention.

DETAILED DESCRIPTION

Accordingly, the present disclosure is directed to methods of patterning deposit
15 metals on polymeric film substrates. The polymeric film substrates have a relief pattern (or structure or microstructure) on one or both of their major surfaces. Polymeric film substrates with a relief pattern on a major surface are said to be structured or microstructured.

By having a relief pattern, what is meant is that the surface includes a
20 topographical pattern, for example a pattern of recessed regions (e.g., channels, wells, grooves) or a pattern of raised regions (e.g., ridges, posts, hemispheres). The polymer film substrates can be structured by cast-and-cure microreplication, or embossing, for example, and then these structured film substrates can have functionalizing molecules selectively placed on raised regions of the structured film substrate.

25 These functionalizing molecules can serve as a mask for subsequent additive patterning via, for example, electroless plating. While the present invention is not so limited, an appreciation of various aspects of the invention will be gained through a discussion of the example provided below.

For the following defined terms, these definitions shall be applied, unless a
30 different definition is given in the claims or elsewhere in this specification.

“Region” refers to a contiguous fractional portion of an entire surface, e.g., of a substrate surface. A raised region refers to a surface region that projects away from

adjacent regions of the major surface and has a height. A recessed region refers to a surface region that extends inward with respect to adjacent regions of a major surface and has a depth. A raised region and/or a recessed region can be a discrete region, where the adjacent recessed and/or raised region (respectively) surrounds the discrete region on all sides. Alternatively, the raised or recessed region can be a generally contiguous region that extends generally linearly along a length or width of the surface and adjacent regions of the major surface do not surround the contiguous region on all sides. A raised surface region of a substrate is in general that portion of a substrate surface that comes into contact with the flat surface of another object when the substrate surface and the flat surface (i.e., non-structured and planar) of the other object are made to touch, when the flat object is larger in area than the raised region and any adjacent recessed regions. The recessed surface region or regions of a substrate are in general the surface regions complementary to the raised surface regions, as just described. By complementary, what is meant is that all of the raised surface region or regions and all of the recessed surface region or regions combine to define essentially the entire major surface.

Forming a layer of functionalizing material "selectively," refers to forming a layer of functionalizing material on one surface region and not forming a layer of functionalizing on another surface region. For a layer of functionalizing material to be deposited selectively on a substrate surface, it is not deposited on the entire substrate surface. That is, the layer of functionalizing material forms a pattern on the substrate surface.

A polymeric "film" substrate is a polymer material in the form of a flat sheet that is sufficiently flexible and strong to be processed in a roll-to-roll fashion. By roll-to-roll, what is meant is a process where material is wound onto or unwound from a support, as well as further processed in some way. Examples of further processes include coating, slitting, blanking, exposing to radiation, or the like. Polymeric films can be manufactured in a variety of thickness, ranging in general from about 5 micrometers to 1000 micrometers. In many embodiments, polymeric film thicknesses range from about 25 micrometers to about 500 micrometers, or from about 50 micrometers to about 250 micrometers, or from about 75 micrometers to about 200 micrometers. For films that include a relief structure on one or both major surfaces, what is meant by thickness of the film is the average thickness across the area of the film.

Depositing a metal "selectively," refers to depositing metal on one surface region and not depositing the metal on another surface region. For a metal to be deposited selectively on a substrate surface, it is not deposited on the entire substrate surface. That is, the deposit metal forms a pattern on the substrate surface.

5 The terms "deposit metal" and "metallic deposit" and "deposited metal" are used interchangeably and refer to a metal deposited on a substrate. The deposit metal is usually formed from an electroless plating solution. The deposit metal can be in the form of a pattern such as linear traces in an electrical circuit, contact pads on an electrical device, or large-area coatings.

10 An "electrolessly deposited metal" is a metal deposited by electroless deposition (e.g., that includes microstructural signature of electroless deposition). For example, copper deposited electrolessly from formaldehyde baths includes microscopic hydrogen voids, particularly at grain boundaries, that are observable using transmission electron microscopy. Most commercial electroless nickel baths include reducing agents based on
15 hypophosphites, borohydrides, or amine boranes, leading to the presence of boron or phosphorous in the deposit. An electrolessly deposited nickel coating has been reported to include a banded microstructure normal to the growth direction that was observable using optical microscopy. Nickel deposited electrolessly from hypophosphite baths has been reported to include isolated regions of enriched phosphorus, separated by essentially pure
20 nickel. Annealed electroless nickel deposits are reported to include inclusions of nickel boride or nickel phosphide observable, which are observable using transmission electron microscopy.

25 A "functionalizing molecule" refers to molecules that attach to a substrate surface (or coated substrate surface) via a chemical bond. The functionalizing molecule can passivate or activate the surface region it is attached to. In many embodiments, the functionalizing molecules form a self-assembled monolayer.

30 A "self-assembled monolayer" refers to a single layer of molecules that are attached (e.g., by a chemical bond) to a surface and that have adopted a preferred orientation with respect to that surface and even with respect to each other. Self-assembled monolayers have been shown to cover surfaces so completely that the properties of that surface are changed. For example, application of a self-assembled monolayer can result in a surface energy reduction.

Examples of chemical species that are suitable for forming self-assembled monolayers include organic compounds such as organosulfur compounds, silanes, phosphonic acids, benzotriazoles, and carboxylic acids. Examples of such compounds are discussed in the review by Ulman (A. Ulman, "Formation and Structure of Self-Assembled Monolayers," *Chem. Rev.*, 96, 1533-1554 (1996)). In addition to organic compounds, certain organometallic compounds are useful for forming self-assembled monolayers. Examples of organosulfur compounds that are suitable for forming self-assembled monolayers include alkyl thiols, dialkyl disulfides, dialkyl sulfides, alkyl xanthates, and dialkylthiocarbamates. Examples of silanes that are suitable for forming self-assembled monolayers include organochlorosilanes and organoalkoxysilanes. Examples of phosphonic acid molecules that are suitable for forming self-assembled monolayers are discussed by Pellerite et al. (M. J. Pellerite, T. D. Dunbar, L. D. Boardman, and E. J. Wood, "Effects of Fluorination on Self-Assembled Monolayer Formation from Alkanephosphonic Acids on Aluminum: Kinetics and Structure," *Journal of Physical Chemistry B*, 107, 11726-11736 (2003)). Chemical species that are suitable for forming self-assembled monolayers can include, for example, hydrocarbon compounds, partially fluorinated hydrocarbon compounds, or perfluorinated compounds. The self-assembled monolayer can include two or more different chemical species. In the use of two or more different chemical species, the chemical species may exist in the self-assembled monolayer as a mixture or with a phase-separated morphology.

Illustrative useful molecules for forming a self-assembled monolayer include, for example, (C₃-C₂₀)alkyl thiols, or (C₁₀-C₂₀)alkyl thiols, or (C₁₅-C₂₀)alkyl thiols. The alkyl groups can be linear or branched and can be substituted or unsubstituted with substituents that do not interfere with the formation of a self-assembled monolayer.

The self-assembled monolayer can be formed on an inorganic material-coated polymeric surface (e.g., a metal-coated polymeric surface) using a variety of methods. In many embodiments, the self-assembled monolayer is applied to the metal coated polymeric substrate raised regions by contacting the selected or raised regions with a plate having the self-assembled monolayer molecules disposed therein or thereon. In many embodiments, the plate is an elastomeric transfer element that delivers functionalizing molecules to the substrate. The plate may be planar, cylindrical, or other shape, as desired.

In many embodiments, the plate having the self-assembled monolayer molecules disposed therein or thereon is featureless and the pattern of self-assembled monolayer on the polymeric film substrate is defined by the raised surface regions of the polymeric film substrate. By featureless, what is meant is that the plate is smooth (lacks a relief structure) on the scale of the relief structure on the film substrate surface. As compared with prior art methods (e.g., microcontact printing, U. S. Patent No. 5,512,131) the present disclosure allows for the placement of functionalizing molecules (e.g., self-assembled monolayers) onto polymeric film surfaces in patterns without the need to limit slippage of the plate with respect to the film substrate. In microcontact printing, the relief-structured stamp and the flat substrate must be contacted and separated without slippage in order to preserve pattern fidelity. This is especially challenging when attempting to continuously microcontact print very small feature sizes roll-to-roll on flexible polymeric film substrates. Roll-to-roll implementation of continuous microcontact printing with polymeric film substrates and small features sizes in the pattern (e.g., less than 10 micrometers, or less than 1 micrometer) poses significant challenges in synchronization (e.g., control of web advance with respect to the printing plate rotation). The present disclosure overcomes these problems by allowing the pattern of transferred functionalizing molecules to be defined by the film substrate relief structure, rather than the combination of printing plate relief and the details of contact and release from the substrate. Also, elastomeric materials are particularly useful for transferring functionalizing molecules (e.g., self-assembled monolayers) to surfaces, but have a tendency to deform under the printing action when structured with a fine-scale relief pattern. The present disclosure allows the pattern of functionalizing molecules on the polymer film substrate to be defined by a potentially more rigid material (substrate itself, rather than the elastomeric printing plate), further assuring ultimate pattern fidelity for the functionalizing molecules, and in turn the deposited metal.

Useful elastomers for forming the plate include silicones, polyurethanes, EPDM rubbers, as well as the range of existing commercially available flexographic printing plate materials (e.g., commercially available from E. I. du Pont de Nemours and Company, Wilmington, Delaware, under the trade name Cyrel®). Polydimethylsiloxane (PDMS) is particularly useful. The plate can be made from a composite material. The elastomer can be a gel material (e.g., co-continuous liquid and solid phases), for example a hydrogel.

The plate can be supported on another material, for example a more rigid material for fixing the shape and size of the plate during use. The plate can be activated during transfer of the functionalizing molecules (e.g., heated, or ultrasonically driven)

An inorganic material (e.g., metallic) coating on the polymeric film substrate can be used to support the self-assembled monolayer. The inorganic material coating can include, for example, elemental metal, metal alloys, intermetallic compounds, metal oxides, metal sulfides, metal carbides, metal nitrides, and combinations thereof.

Exemplary metallic surfaces for supporting self-assembled monolayers include gold, silver, palladium, platinum, rhodium, copper, nickel, iron, indium, tin, tantalum, as well as mixtures, alloys, and compounds of these elements. These metal coatings on the polymeric film substrate can be any thickness such as, for example, from 10 to 1000 nanometers. The inorganic material coating can be deposited using any convenient method, for example sputtering, evaporation, chemical vapor deposition, or chemical solution deposition (including electroless plating). In one embodiment, the inorganic materials coating on the polymeric substrate is any of various solution-applied catalysts (e.g., Pd), as are known in the art.

The term “electroless deposition” refers to a process for the autocatalytic plating of metals. It involves the use of an electroless plating solution that contains a soluble form of the deposit metal together with a reducing agent. The soluble form of the deposit metal is usually an ionic species or a metal complex (i.e., a metal species coordinated to one or more ligands). In many embodiments, electroless deposition does not include the application of electrical current to a work piece that is being coated. The steps involved in electroless plating include the preparation of a film substrate with a catalytic surface (e.g., a metal coated polymeric film substrate surface), followed by immersion of the polymeric film substrate in an appropriate plating bath. The catalytic surface catalyzes the deposition of metal from solution. Once started, plating proceeds by the continued reduction of the solution metal source, catalyzed by its own metal surface, hence the term “autocatalytic.” Metallic deposits that can be formed using electroless deposition include copper, nickel, gold, silver, palladium, rhodium, ruthenium, tin, cobalt, zinc, as well as alloys of these metals with each other or with phosphorous or boron, as well as compounds of these metals with each other or with phosphorous or boron. Suitable reducing agents include, for example, formaldehyde, hydrazine, aminoboranes, and hypophosphite. Suitable metal

surfaces for catalysis of electroless deposition include palladium, platinum, rhodium, silver, gold, copper, nickel, cobalt, iron, and tin, as well as alloys and compounds of the elements with each other or with other elements. The deposit metal and the metal included in the inorganic material coating the polymeric film surface can be the same or different.

In some embodiments, the patterned placement of functionalizing molecules according to the relief pattern of the polymeric film substrate surface is in turn used to control the subsequent selective attachment of activating catalysts for selective electroless deposition. The application of activating catalysts from solution is known in the art (U.S. Patent No. 6,875,475).

Unless otherwise indicated, all numbers expressing feature sizes, amounts, and physical properties used in the specification and claims are to be understood as being modified in all instances by the term “about.” Accordingly, unless indicated to the contrary, the numerical parameters set forth in the foregoing specification and attached claims are approximations that can vary depending upon the desired properties sought to be obtained by those skilled in the art utilizing the teachings disclosed herein.

The recitation of numerical ranges by endpoints includes all numbers subsumed within that range (e.g. 1 to 5 includes 1, 1.5, 2, 2.75, 3, 3.80, 4, and 5) and any range within that range.

As used in this specification and the appended claims, the singular forms “a”, “an”, and “the” encompass embodiments having plural referents, unless the content clearly dictates otherwise. As used in this specification and the appended claims, the term “or” is generally employed in its sense including “and/or” unless the content clearly dictates otherwise.

The term “polymer” will be understood to include polymers, copolymers (e.g., polymers formed using two or more different monomers), oligomers and combinations thereof, as well as polymers, oligomers, or copolymers that can be formed in a miscible blend.

The disclosure generally relates to methods for patterning deposit metals on polymeric film substrates having a relief pattern. In many embodiments, the deposit metal is electrolessly deposited on a film substrate only in recessed regions of the relief pattern. These recessed regions can exhibit a regular or repeating geometric arrangement on the

film substrate, for example an array of polygons or a pattern of traces that define discrete undeposited areas that include an array of polygons. In other embodiments, the recessed regions can exhibit a random arrangement on the polymeric film substrate, for example a random net of traces that define the boundaries of irregular shapes for undeposited areas.

5 In yet another embodiment, the recessed regions can exhibit an arrangement that is not regular, repeating, or random, but that is a specified design which includes or lacks symmetry or repeating shapes. A deposit metal that is patterned can exist on only one region of the film substrate surface or it may exist on more than one region of the film substrate surface; but to be patterned it may not exist on all regions of the film substrate surface.

10 Particularly advantageous approaches for the preparation of a relief pattern onto or into a polymeric film surface include replication or forming a microstructure or relief pattern with a mechanical tool. Mechanical tools form a microstructure or relief pattern onto or into the polymeric film surface by embossing, scribing, or molding the microstructure or relief pattern onto or into the polymeric film substrate surface.

15 Replication includes the transfer of surface structural feature from a master tool (e.g., a mechanical tool) to another material and includes embossing or molding. Methods involving replication are noteworthy for the ease and speed with which materials with structured surfaces can be generated. Also noteworthy is the small size that can be achieved for surface structure features that are generated through replication. Nanoscale features with size less than 10 nanometers, can be replicated.

20 Replication can be achieved in any number of ways. One illustrative method for replicating the surface structural features or relief pattern of a master mechanical tool into the surface of another material is through thermal embossing (U.S. Pat. No. 5,932,150).

25 Thermal embossing involves the pressing of a master mechanical tool against a deformable material, causing the surface structure of the master tool to deform the surface of the deformable material, thereby generating a negative replica of that master tool surface. Materials that can be embossed with surface structure or relief pattern include, for example, soft metals and organic materials such as polymers. Examples of soft metals that can be embossed include indium, silver, gold, and lead. Polymers suitable for thermal embossing include thermoplastics. Examples of thermoplastics include polyolefins, polyacrylates, polyamides, polyimides, polycarbonates, and polyesters. Further examples

of thermoplastics include polyethylene, polypropylene, poly(methylmethacrylate), polycarbonate of bisphenol A, poly(vinyl chloride), poly(ethylene terephthalate), and poly(vinylidene fluoride). For the preparation of thermally embossed materials, it is often convenient and useful to start with material in film form. Optionally, a film for embossing
5 can include multiple layers (U.S. Pat. No. 6,737,170 and U.S. Pat. No. 6,788,463).

Another approach for replicating the surface structure of a master mechanical tool into the surface of polymeric film is to cure a flowable precursor to the polymer while in contact with the master mechanical tool. Curing a flowable precursor to a polymer while in contact with the master mechanical tool is one form of molding. Examples of flowable
10 precursors include neat monomers, mixtures of monomers, solutions of monomers or polymers that may include removable solvent, and uncrosslinked polymers. Generally, a precursor to the cured polymer can be cast onto a master mechanical tool or into a mold, followed by curing (U.S. Pat. No. 4,576,850). Curing refers to the development of increased elastic modulus, usually by way of a chemical reaction. Curing to develop
15 elastic modulus can include heating, addition of a catalyst, addition of an initiator, or exposure to ultraviolet light, visible light, infrared light, X-rays, or an electron beam. Once the polymer has been cured, it can be removed as a solid from contact with the master tool or mold. Examples of polymers suitable for molding include polyacrylates, polyimides, epoxies, silicones, polyurethanes, and some polycarbonates. Polymers that are
20 particularly useful for forming structured or microstructured polymeric films by molding and that suitable for roll-to-roll processing include polyacrylate and polymethacrylate. Some of these polymers also have optical properties that make them especially well-suited for certain display and sensor applications wherein they would support a patterned conductor (e.g., EMI shielding films), particularly polyacrylates.

Another illustrative method for generating a microstructure or relief pattern on the surface of a polymeric film substrate includes using a mechanical tool is by scribing. "Scribing" refers to the application of a stylus to an otherwise unstructured surface and pressing or translating the stylus on the surface, generating surface microstructure. A stylus tip may be made of any material such as, for example, a metal, ceramic, or polymer.
30 A stylus tip may include diamond, aluminum oxide, or tungsten carbide. A stylus tip may also include a coating, for example a wear-resistant coating such as titanium nitride.

The structured polymeric film substrate can be prepared from a suitable polymeric material that has sufficient mechanical properties (e.g., strength and flexibility) to be processed in a roll-to-roll apparatus. Examples of such polymers include thermoplastic polymers. Examples of useful thermoplastic polymers in the present disclosure include polyolefins, polyacrylates, polyamides, polyimides, polycarbonates, polyesters, and biphenol- or naphthalene-based liquid crystal polymers. Further examples of useful thermoplastics in the present disclosure include polyethylene, polypropylene, poly(methylmethacrylate), polycarbonate of bisphenol A, poly(vinyl chloride), polyethylene terephthalate, polyethylene naphthalate, and poly(vinylidene fluoride). Some of these polymers also have optical properties (e.g., transparency) that make them especially well-suited for certain display and sensor applications wherein they would support a patterned conductor (e.g., EMI shielding films), particularly polycarbonates and polyesters. Others of these polymers have thermal and electrical properties that make them especially well-suited for certain electrical circuit applications wherein they would support a patterned conductor (e.g., support and interconnection of electronic components), particularly polyimides and liquid crystal polymers.

FIGs. 1A–1H is a schematic diagram of an illustrative method of patterning a deposit metal **165** on a polymeric film substrate **105**. The polymeric film substrate **105** is replicated **100** with a mechanical tool **120** to form a structured polymeric film substrate **111** having a major surface **104** with a relief pattern including a recessed region **108** and an adjacent raised region **106**. The mechanical tool **120** can be applied (as shown by the downward arrows) to a major surface **104** of the polymeric substrate **105**. In the illustrated embodiment, the mechanical tool **120** forms relief pattern recessed regions **108** that extend into the major surface **104** of the polymeric film substrate **105**. The recessed regions **108** have a depth and a width defined by a recessed surface **107**. In some embodiments, the recess regions **108** are generally parallel channels having a depth in a range from 0.1 to 10 micrometers and a width in a range from 0.25 to 50 micrometers, and a distance between adjacent parallel recess regions **108** is in a range from 100 micrometers to 1 centimeter.

The polymeric film substrate **105** can be any useful polymeric material, as described above. In many embodiments, the polymeric film substrate **105** is a flexible polymeric film that can be utilized in a roll-to-roll apparatus (shown in **FIG. 3**). In some

embodiments, the polymeric film substrate **105** is a flexible transparent polymeric film that can be utilized in a roll-to-roll apparatus (shown in **FIG. 3**).

A first material **110** is deposited on the major surface **104** including the raised regions **106** and recessed regions **108** of the polymeric film substrate **105** to form a coated polymeric film substrate **112**. In many embodiments, the first material **110** is a metal layer, as described above, and is applied as described above.

A layer of functionalizing material **131** is selectively formed **113** on the raised region **106** to form a functionalized raised region **106** and unfunctionalized recess regions **108**. The layer of functionalizing material **131** can be selectively applied to the raised region **106** with a featureless plate **130** that can be elastomeric. The featureless plate **130** transfers the functionalizing material **131** to the raised region **106** where the featureless plate **130** contacts the raised region **106**. The featureless plate **130** does not transfer the functionalizing material **131** to the recessed regions **108** since the featureless plate **130** does not contact the surface **107** of recessed region **108**. Thus, the relief structure of the polymeric film substrate **105** dictates the regions to which the functionalizing material **131** is selectively transferred to the polymeric film substrate **105**. In many embodiments, the functionalizing material **131** is a self-assembled monolayer **131**, as described above.

The selectively functionalized polymeric film substrate **114** is then exposed **115** to an electroless plating solution **160** including a soluble form of a deposit metal. The deposit metal can be deposited **116** selectively on the unfunctionalized recessed regions **108** to form a deposit metal pattern **165**. In one embodiment, the deposit metal **165** includes copper and the first material **110** is formed from gold and/or titanium. In some embodiments, at least a portion of the first material **110** can be removed **117** via etching after deposition of the deposit metal **165**. The removal of the first material **110** also removes the functionalizing material **131**.

FIG. 2 is a schematic diagram of another illustrative method of patterning a deposit material on a polymeric film substrate. The illustrated polymeric film substrate **200** includes two or more polymeric layers where the first polymeric layer **204** is a base layer and a second layer **205** is disposed on the first layer **204**. The first polymeric layer **204** and the second polymeric layer **205** can be formed from the same or different polymer material. In some embodiments, the first polymeric layer **204** is formed from a polyester such as polyethylene terephthalate or polyethylene naphthalate, and the second polymeric

layer **205** is formed from a polyacrylate. In many embodiments, the first polymeric layer **204** and the second polymeric layer **205** form a flexible and/or transparent film or web. In many embodiments, the polymeric film substrate **200** is a flexible and/or transparent polymeric film that can be utilized in a roll-to-roll apparatus (shown in **FIG. 3**).

5 The polymeric film substrate **200** has a major surface **203** with a relief pattern including one or more raised regions **208** that project from the major surface **203** and one or more recessed regions **206** are adjacent to the raised regions **208**. The raised regions **208** can be formed by any of the replication methods described herein. The raised regions **208** are defined by raised region surfaces **207**. The raised regions **208** have a height and a width defined by a raised region surface **207**. In some embodiments, the raised regions **208** are generally parallel ridges having a height in a range from 0.5 to 10 micrometers and a width in a range from 0.5 to 10 micrometers, and a distance between adjacent parallel raised regions **208** is in a range from 100 to 500 micrometers.

10 A first material **210** is deposited on the recessed regions **206** and raised regions **208** to form a coated polymeric film substrate **211**. In many embodiments, the first material **210** is a metal layer, as described above and is deposited as described above.

15 A layer of functionalizing material **231** is selectively formed **212** on the raised regions **208** to form a functionalized raised region surface **207** and an unfunctionalized recess regions **206**. The layer of functionalizing material **231** can be applied to the raised regions **208** with a featureless plate **230** that can be elastomeric. The featureless plate **230** transfers the functionalizing material **231** to the raised regions **208** where the featureless plate **230** contacts the raised regions **208**. The featureless plate **230** does not transfer the functionalizing material **231** to the recessed regions **206** since the featureless plate **230** does not contact the recessed regions **206**. Thus, the relief structure of the polymeric substrate dictates the regions the functionalizing material **231** is selectively transferred to. In many embodiments, the functionalizing material is a self-assembled monolayer **231**, as described above.

20 The selectively functionalized polymeric film substrate **213** is then exposed **214** to an electroless plating solution **260** including a soluble form of a deposit metal. The deposit metal can be deposited **215** selectively on the unfunctionalized recess regions **206** to form a deposit metal pattern **265**. In one embodiment, the deposit metal **265** includes copper and the first material **210** is formed from gold and/or titanium. In some

embodiments, at least a portion of the first material **210** can be removed **216** via etching after deposition of the deposit metal **265**. The removal of the first material **210** also removes the functionalizing material **231**.

FIG. 3 is a schematic diagram of an illustrative roll-to-roll apparatus **300**. The illustrated roll-to-roll apparatus **300** includes an input roll **310** and a take-up roll **320** and a polymeric film **311**. The method illustrated in **FIG. 1** and **FIG. 2** can be carried out at box **330** on the polymeric film **311**. The deposit metal patterned polymeric film **312** can be wound onto the take-up roll, as shown, further processed, as desired.

The deposit metal on the polymeric film substrate may be described as having an area shape and an area size on the polymeric film surface, as well as a thickness. The area shape of the deposit metal can exhibit a regular or repeating geometric arrangement on the polymeric film, for example an array of deposit metal polygons or a pattern of deposit metal traces that define the boundaries of discrete undeposited areas that include an array of polygons. In other embodiments, the deposit metal shapes may exhibit a random arrangement on the substrate, for example a random net of traces that define the boundaries of irregular shapes for undeposited areas. In yet another embodiment, the deposit metal shapes may exhibit an arrangement that is not regular, repeating, or random, but that is a specified design which includes or lacks symmetry or repeating geometric elements. In one embodiment, a shape for the deposit metal that is useful for making a light-transmitting, EMI shielding material is a square grid, which includes traces of the deposit metal characterized by a width, thickness, and pitch. Other useful shapes for making a light-transmitting, EMI shielding material include continuous metallic traces that define open areas that have the shape of a regular hexagon (deposited metal pattern is a hexagonal net) and that are arranged in closely packed order. In order to fabricate continuous metal traces in the form a square grid, useful relief patterns for the polymeric film substrate include a square array of raised square regions (oriented parallel to the grid). In order to fabricate continuous metal traces in the form of a hexagonal net, useful relief patterns for the polymeric film substrate include a hexagonal array of raised hexagonal regions (with edges oriented parallel to the net trace directions). In summary, for fabricating EMI shielding patterns of deposited conductor, some useful relief patterns include an array of discrete raised regions each surrounded by a contiguous recessed region.

In some embodiments, the smallest area dimension for the deposit metal shapes, for example the width of a linear trace of deposit metal, can range from 100 nanometers to 1 millimeter, or from 500 nanometers to 50 micrometers, or from 1 micrometer to 25 micrometers, or from 1 micrometer to 15 micrometers, or from 0.5 to 10 micrometers. In one illustrative embodiment for making a light-transmitting EMI shielding material, the width of linear traces of deposit metal is in a range from 5 micrometers to 15 micrometers, or from 0.25 to 10 micrometers; the thickness is in a range from 0.25 to 10 micrometers, or from 1 micrometer to 5 micrometers; and the pitch is in the range from 25 micrometers to 1 millimeter, or from 100 to 500 micrometers. The largest area dimension for the deposit metal shapes above, for example the length of a linear trace of deposit metal, can range from 1 micrometer to 5 meters, or from 10 micrometers to 1 meter. For making a light-transmitting EMI shielding material, a sheet of EMI shielding material, the length of linear traces of deposit metal can be in the range from 1 centimeter to 1 meter, for example.

In some embodiments, the relief pattern of the major surface of the polymeric film substrate includes a plurality of recessed regions in the form of linear traces that are isolated from each other by a contiguous raised region. The pattern of deposited metal that can be fabricated according to the invention using the aforementioned relief pattern is useful for forming electrical circuits that are useful for supporting electronic components or for sensing applications. By linear traces, what is meant is that at least a portion of the recessed region includes a geometric feature characterized by a length that exceeds its width by a factor of at least five. A linear trace may be straight or curved, and may have an angular turn. Preferably, the linear traces have a width between 0.25 and 50 micrometers and a depth between 0.1 and 10 micrometers.

The present invention should not be considered limited to the particular examples described herein, but rather should be understood to cover all aspects of the invention as fairly set out in the attached claims. Various modifications, equivalent processes, as well as numerous structures to which the present invention can be applicable will be readily apparent to those of skill in the art to which the present invention is directed upon review of the instant specification.

EXAMPLES

Unless otherwise noted, all chemical reagents and solvents were obtained from Aldrich Chemical Co., Milwaukee, WI.

5

Example 1

Substrate Preparation

10 A 250 micrometer thick film of transparent polycarbonate (available under the trade name Lexan from GE Plastics division (Pittsfield, MA) of General Electric Company (Fairfield, CT)) was thermally embossed with a relief pattern of recessed gridlines complemented by raised squares. The embossing tool was fabricated from a round 10 centimeter diameter plate of fused quartz using photolithography and reactive ion etching methods. The tool included 10 micrometer wide ridges that were approximately 10
15 micrometers high and that defined the lines of a square grid with a pitch of 200 micrometers. Embossing was carried out by pressing, with 10,000 newtons of force, the embossing tool against the polycarbonate film at 176°C for 15 minutes using a Model AUTO M laminating press (available from Carver, Inc., Wabash, IN). The embossed film included 10 micrometer wide channels that were approximately 10 micrometers deep and
20 that defined the lines of a square grid with a pitch of 200 micrometers. Once embossed, the polycarbonate film was first metallized by evaporation with 15 angstroms of titanium to form a tie layer followed by a 600 angstroms gold layer using a thermal evaporator (available from Kurt J. Lesker Co., Pittsburgh, PA).

25 Elastomer Plate Preparation

Two essentially featureless plates of polydimethylsiloxane (PDMS, Sylgard® 184 from Dow Corning Corporation of Midland, MI) were cast against a single crystal of silicon. One plate was partially submerged in a 5 millimolar solution of octadecanethiol in ethanol for two days with cast-flat side exposed to air, in order to saturate the plate. The
30 second plate was then placed by hand in contact with and on top of the first plate for 30 minutes to create an inked surface of the second plate.

The metallized, structured surface of the polycarbonate film was then placed by hand in contact with the inked surface of second plate to transfer a self-assembled monolayer (SAM) of octadecanethiol to the raised regions of the polycarbonate film, leaving the 10 micrometer wide recesses (or channels) unfunctionalized (without SAM).

5

Electroless Plating and Etching

The SAM printed substrate having unfunctionalized 10 micrometer wide recesses, was placed in an electroless copper plating solution (M-COPPER 85C Mac Dermid, Inc., of Waterbury, CT). Copper was electrolessly and selectively plated only in the unfunctionalized 10 micrometer wide recesses. The electrolessly metallized film was then UV-ozone cleaned by exposing the film to oxygen while illuminating with a low-pressure quartz mercury vapor lamp, thereby removing the SAM from the raised, non-copper deposited regions. The gold was etched off from in the non-copper deposited regions using a bath containing an aqueous solution consisting of iodine (0.5M) and potassium iodide (0.5M).

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The resulting substrate was a flexible, structured substrate with patterned copper deposited in the recess regions.

WE CLAIM:

1. A method of patterning a deposit metal on a polymeric film substrate comprising:
providing a polymeric film substrate having a major surface with a relief pattern
5 comprising a recessed region and an adjacent raised region;
depositing a first material onto the major surface of the polymeric film substrate to
form a coated polymeric film substrate;
forming a layer of a functionalizing material selectively onto the raised region of
the coated polymeric film substrate to form a functionalized raised region and
10 an unfunctionalized recessed region; and
depositing electrolessly a deposit metal selectively on the unfunctionalized
recessed region, forming a deposit metal patterned polymeric film substrate.
2. A method according to claim 1 wherein the providing step comprises providing a
15 transparent polymeric film substrate.
3. A method according to claim 1 wherein the providing step comprises providing a
polymeric film substrate comprising a polymer selected from the group of polyolefins,
polyamides, polyimides, polycarbonates, polyesters, polyacrylates, polymethacrylates, and
20 liquid crystal polymers.
4. A method according to claim 1 wherein the depositing a first material step
comprises depositing a metal selected from the group of gold, silver, palladium, platinum,
rhodium, copper, nickel, iron, indium, tin, and mixtures, alloys, and compounds thereof
25 onto the polymeric film substrate.
5. A method according to claim 1 wherein the forming step comprises forming a layer
of a self-assembled monolayer selectively onto the raised region of the coated polymeric
film substrate.

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6. A method according to claim 1 wherein the forming step comprises applying the functionalizing material selectively onto the raised region of the coated polymeric film substrate with an elastomeric plate.

5 7. A method according to claim 1 wherein the forming step comprises applying the functionalizing material selectively onto the raised region of the coated polymeric film substrate with a featureless elastomeric plate.

10 8. A method according to claim 1 further comprising forming the major surface with a relief structure by molding or embossing the polymeric film substrate with a mechanical tool.

15 9. A method according to claim 1 wherein the depositing electrolessly step comprises depositing electrolessly a deposit metal selected from the group consisting of copper, nickel, gold, silver, palladium, rhodium, ruthenium, tin, cobalt, and zinc.

10. A method according to claim 1 further comprising removing the functionalizing material and the first material from the raised region after the depositing electrolessly step.

20 11. A method according to claim 1 wherein the forming step comprises forming a self-assembled monolayer selectively onto the raised region and the self assembled monolayer comprises a chemical species selected from the group consisting of organosulfur compounds, silanes, phosphonic acids, benzotriazoles, and carboxylic acids.

25 12. A method according to claim 1 wherein the method of patterning a deposit metal on a polymeric film substrate is performed with a roll-to-roll processing apparatus.

13. A method according to claim 1 wherein the relief pattern comprises an array of discrete raised regions each surrounded by a contiguous recessed region.

30

14. A method according to claim 2 wherein the relief pattern comprises plurality of recessed regions in the form of linear traces that are isolated from each other by a contiguous raised region

5 15. A method according to claim 14 wherein the linear traces have a width of 0.25 micrometers to 50 micrometers and a depth of 0.1 micrometers to 10 micrometers.

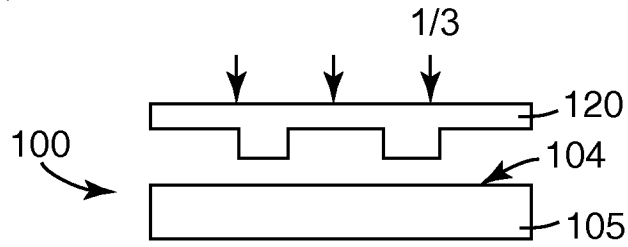
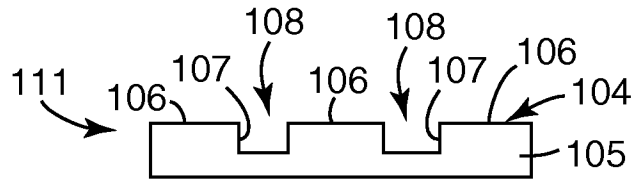
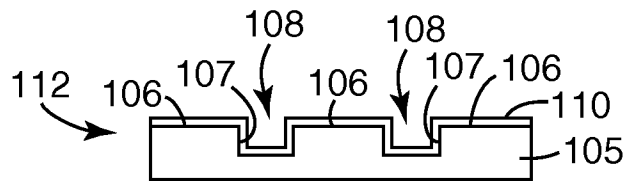
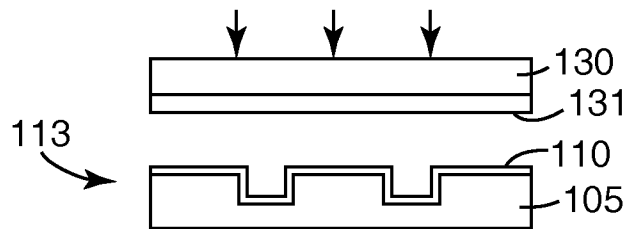
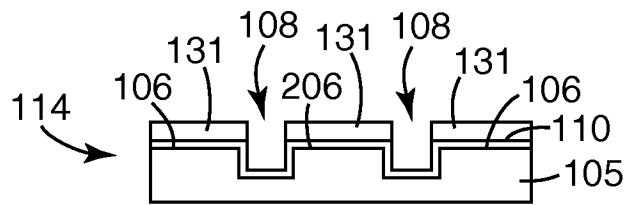
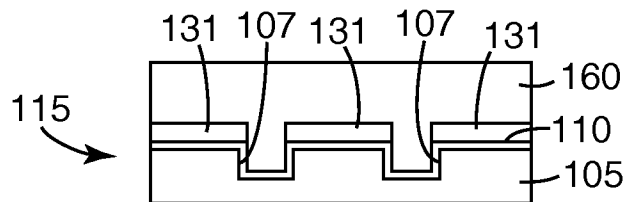
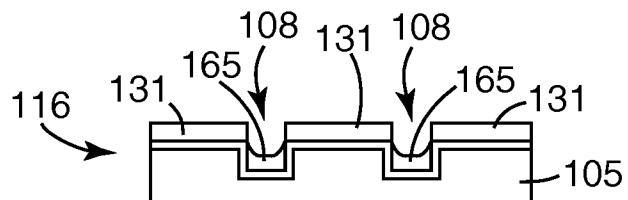
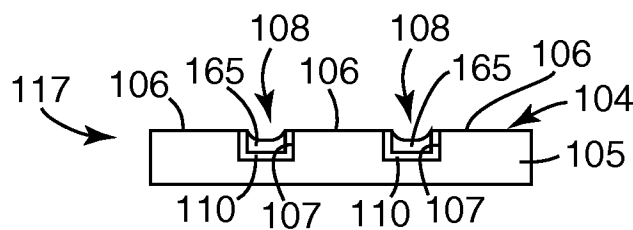
16. An article comprising a polymeric film having:
a major surface with a relief structure comprising:
10 a raised region and an adjacent recessed region; and
functionalizing molecules selectively placed onto the raised region.

17. An article according to claim 16, further comprising a first material deposited on the major surface and disposed between the substrate and the functionalizing molecules in
15 the raised region.

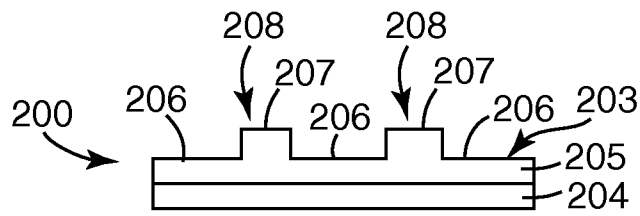
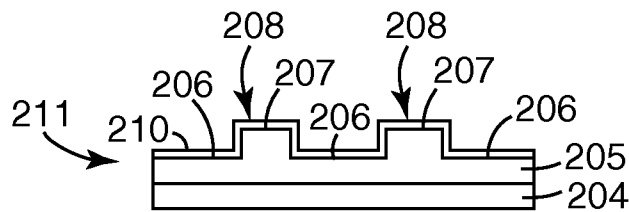
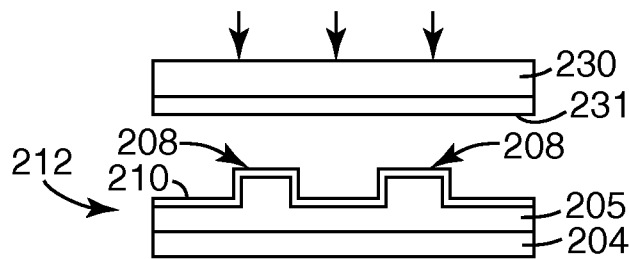
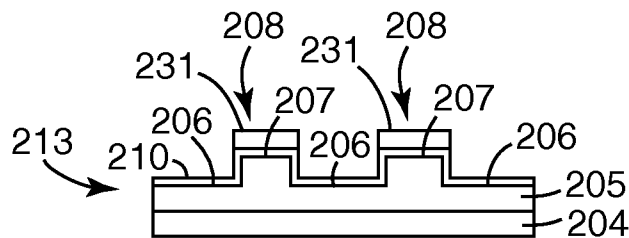
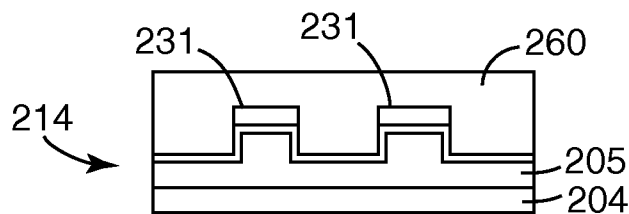
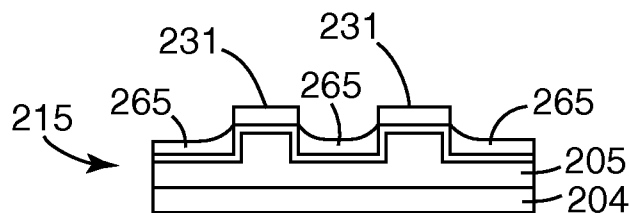
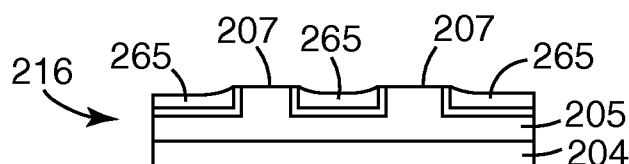
18. An article of claim 16, further comprising electrolessly deposited metal selectively placed onto the recessed region.

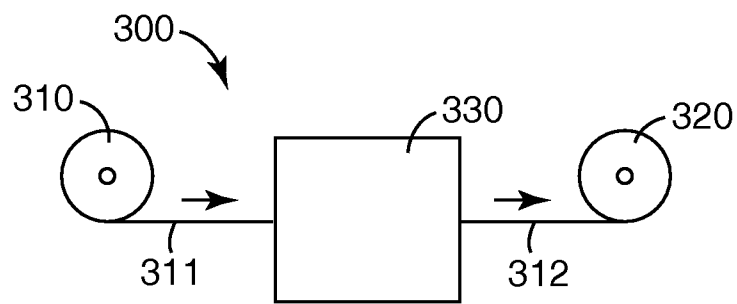
20 19. The article of claim 16, wherein the functionalizing molecules are in the form of a self-assembled monolayer.

20. The article of claim 16, wherein the polymeric film has a thickness between 5 micrometers and 1000 micrometers and comprises a polymer selected from the group of
25 polyimide, polyethylene, polypropylene, polyacrylate, poly(methylmethacrylate), polycarbonate, poly(vinyl chloride), polyethylene terephthalate, polyethylene naphthalate, and poly(vinylidene fluoride), polymethacrylate, and liquid crystal polymers.

*Fig. 1A**Fig. 1B**Fig. 1C**Fig. 1D**Fig. 1E**Fig. 1F**Fig. 1G**Fig. 1H*

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*Fig. 2A**Fig. 2B**Fig. 2C**Fig. 2D**Fig. 2E**Fig. 2F**Fig. 2G*

*Fig. 3*